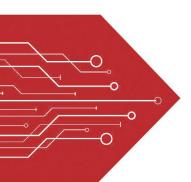
MSKSEMI















ESD

TVS

TSS

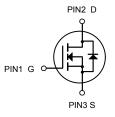
MOV

GDT

PLED

Broduct data sheet





N-Channel MOSFET

Description

The SI2300DS-T1-MS uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 20V I_D = 6 A$

 $R_{DS(ON)}$ < 27m Ω @ V_{GS} =4.5V

Application

Battery protection

Load switch

Uninterruptible power supply

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Symbol	Parameter		Limit	Unit	
V _{DS}	Drain-Source Voltage		20	V	
V _G s	Gate-Source Voltage		±12	V	
	Continuous Drain Current	T _A =25℃	6		
l _D		T _A =70°C	3.6	A	
Ірм	Drain Current-Pulsed (Note 1)		15	Α	
P _D	Maximum Power Dissipation	1.25	W		
TJ,Tstg	Operating Junction and Storage Temperature Range		-55 To 150	$^{\circ}\!\mathbb{C}$	
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)		100	°C/W	

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	20	22.5	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =20V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	Igss	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.65	1.0	V
	_	V _{GS} =4.5V, I _D =4.0 A	-	22	27	mΩ
Drain-Source On-State Resistance	Rds(on)	V _{GS} =2.5V, I _D =4.5A	-	28	40	mΩ
Forward Transconductance	grs	V _{DS} =10V,I _D =4A	-	10	-	S
Input Capacitance	C _{lss}		-	500	-	PF
Output Capacitance	Coss	V _{DS} =8V,V _{GS} =0V,	-	295	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	96	-	PF
Turn-on Delay Time	td(on)		-	11	-	nS
Turn-on Rise Time	t _r	V _{DD} =10V,I _D =1A	-	30	-	nS
Turn-Off Delay Time	td(off)	V_{GS} =4.5V, R_{GEN} =6 Ω	-	35	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg		-	10	15	nC
Gate-Source Charge	Q _{gs}	V _{DS} =10V,I _D =3A,V _{GS} =4.5V	-	2.3	-	nC
Gate-Drain Charge	Q _{gd}	1	-	2.9	-	nC
Diode Forward Voltage (Note 3)	Vsp	V _{GS} =0V,I _S =1A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	4.5	Α

Notes:

- **1.** Repetitive rating: pulse width limited by maximum junction temperature.
- 2. Surface mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse test: pulse width $\leq 300 \mu s$, duty cycle $\leq 2\%$.
- 4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

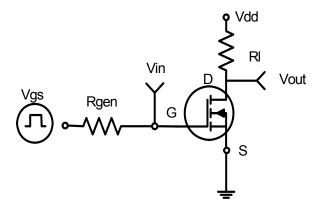


Figure 1:Switching Test Circuit

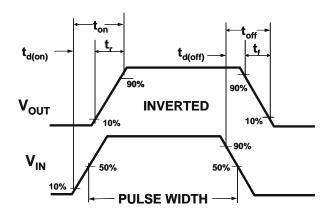


Figure 2:Switching Waveforms

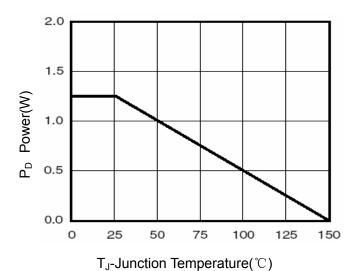


Figure 3 Power Dissipation

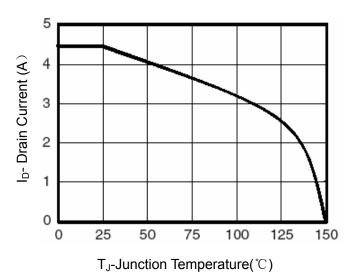


Figure 4 Drain Current

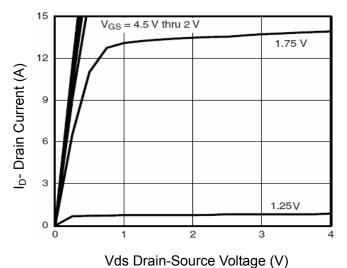


Figure 5 Output Characteristics

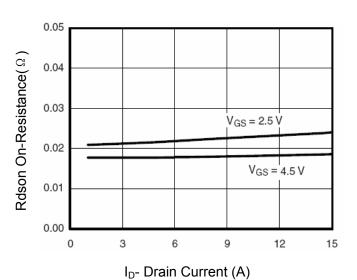


Figure 6 Drain-Source On-Resistance



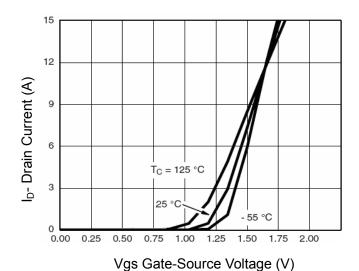
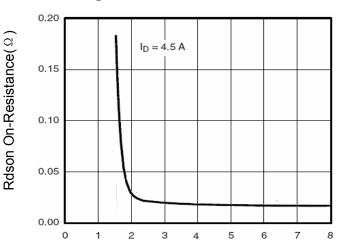


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V) **Figure 9 Rdson vs. Vgs**

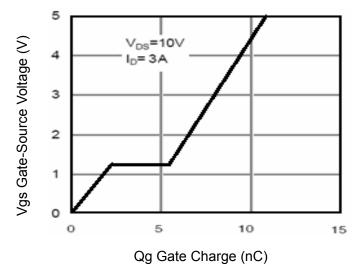


Figure 11 Gate Charge

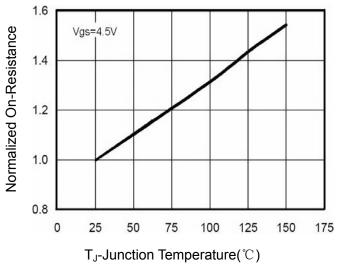


Figure 8 Drain-Source On-Resistance

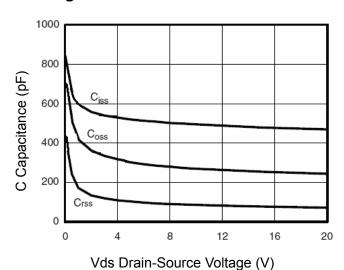
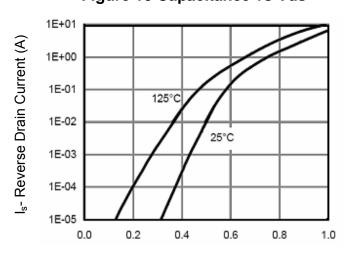


Figure 10 Capacitance vs Vds

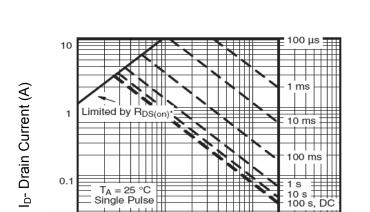


Vsd Source-Drain Voltage (V)

Figure 12 Source- Drain Diode Forward

100





Vds Drain-Source Voltage (V)

0.01

Figure 13 Safe Operation Area

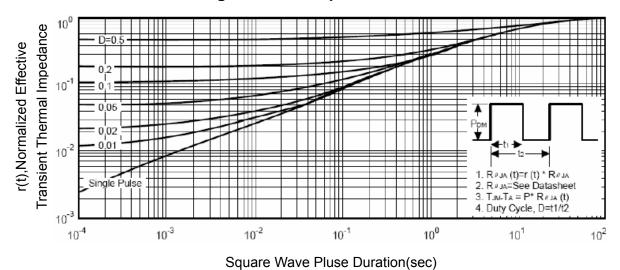
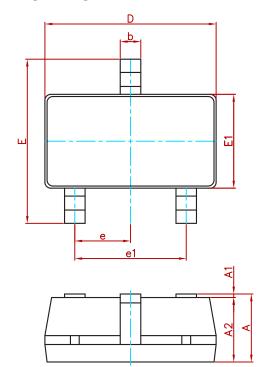
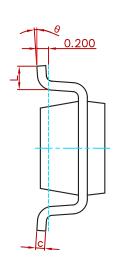


Figure 14 Normalized Maximum Transient Thermal Impedance



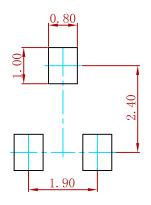
PACKAGE MECHANICAL DATA





Symbol	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
Е	2.650	2.950	0.104	0.116
е	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
Α	0°	8°	0°	8°

Suggested Pad Layout



- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SI2300DS-T1-MS	SOT-23-3L	3000



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 IRF40H233XTMA1 IPSA70R950CEAKMA1 IPSA70R2K0CEAKMA1 STU5N65M6 C3M0021120D